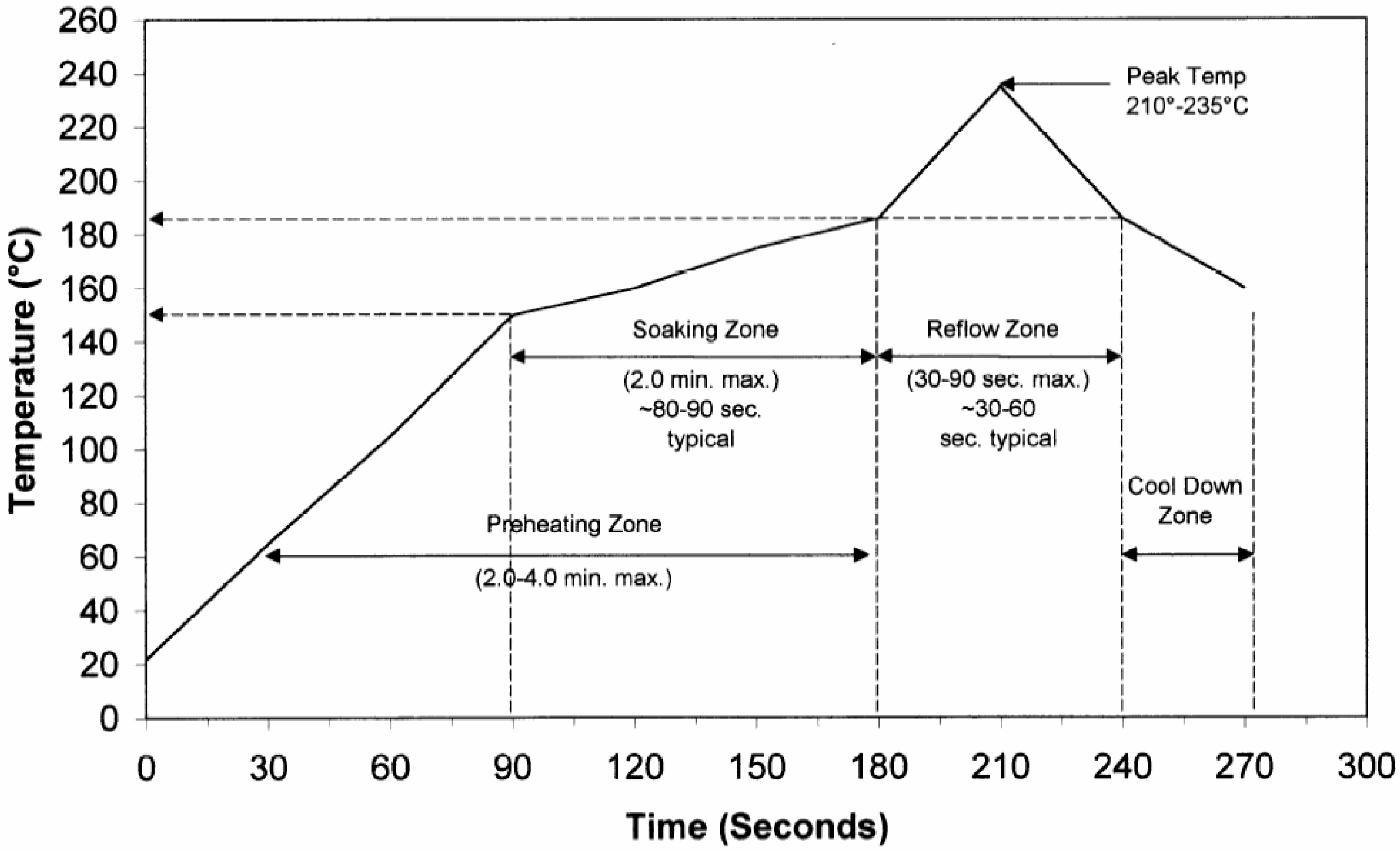
VG-469 Solder Reflow Profile



A typical reflow profile. In the first zone, preheating should not exceed 2.5C/sec to prevent solder ball formation or other defects.

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